

WE ARE PLEASED TO ANNOUNCE THE

Perkins Coie Patent Law

STUDENT FELLOWSHIP
The Fellowship will award a **\$10,000**

academic scholarship and a paid 2L **summer associate position** with the
patent procurement practice group in **Seattle, Washington** OR
Menlo Park, California

A key part of the application process is a 1 page personal statement in which applicants should discuss the background behind their interest in patent law, as well as any personal experience that highlights their commitment to the practice of patent law and/or demonstrates extra potential as a highly successful patent law practitioner.

THE PATENT FELLOWSHIP WILL BE SELECTED ON THE BASIS OF THE FOLLOWING CRITERIA:

- ▶ The individual must be a second-year law student in good standing for the degree of Juris Doctor at an ABA accredited law school.
- ▶ The individual must possess a strong academic record, appropriate technical background and prior relevant experience that demonstrate the level of commitment necessary for a successful patent law career.
- ▶ The individual must be qualified to sit for the Patent Bar Exam.
- ▶ One of the following technical backgrounds is required:
 - Seattle Office** - Electrical Engineering, Mechanical Engineering or Computer Science
 - Menlo Park Office** - Electrical Engineering, Computer Science, or a graduate degree in Chemistry, Chemical Engineering, a Biological Science or Physics

APPLICANTS SHOULD SUBMIT THE FOLLOWING MATERIALS BY WEDNESDAY, SEPTEMBER 5, 2007:

- ▶ Current Resume
- ▶ Transcripts (photocopies acceptable; transcripts need not come directly from registrar) from law school and all technical degrees.
- ▶ 1 page personal statement

IN-OFFICE INTERVIEWS WILL BE CONDUCTED IN SEPTEMBER BEFORE THE FINAL SELECTION PROCESS.



APPLICANTS SHOULD NOTE WHICH OFFICE(S) THEY ARE INTERESTED IN AND SUBMIT ALL MATERIALS FOR THIS POSITION TO:

Perkins Coie Patent Fellowship Program
1201 Third Avenue, Suite 4800
Seattle, WA 98101
Phone: 206-359-8000
Fax: 206-359-9000
email: fellowshiphiring@perkinscoie.com

APPLICATIONS ARE DUE BY SEPTEMBER 5, 2007.